	Application No.	Applicant(s)
Nation of Allowskills	10/815,934	TAKYU ET AL.
Notice of Allowability	Examiner	Art Unit
	Brook Kebede	2823
The MAILING DATE of this communication appe All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RI of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this apport or other appropriate communication GHTS. This application is subject to	plication. If not included will be mailed in due course. THIS
1. \boxtimes This communication is responsive to <u>terminal disclaimer file</u>	ed on December 6, 2005.	
2. ☑ The allowed claim(s) is/are <u>2,3,12 and 13</u> .		
 3. Acknowledgment is made of a claim for foreign priority un a) All b) Some* c) None of the: 1. Certified copies of the priority documents have 		
2. ☐ Certified copies of the priority documents have		
3. ☐ Copies of the certified copies of the priority documents have		
International Bureau (PCT Rule 17.2(a)).	differential flave been received in this	national stage application from the
* Certified copies not received:		
Applicant has THREE MONTHS FROM THE "MAILING DATE" on noted below. Failure to timely comply will result in ABANDONM THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		complying with the requirements
4. A SUBSTITUTE OATH OR DECLARATION must be submi INFORMAL PATENT APPLICATION (PTO-152) which give	itted. Note the attached EXAMINER's reason(s) why the oath or declara	S AMENDMENT or NOTICE OF tion is deficient.
5. CORRECTED DRAWINGS (as "replacement sheets") mus	t be submitted.	
(a) I including changes required by the Notice of Draftsperson		948) attached
1) hereto or 2) to Paper No./Mail Date		
(b) ☐ including changes required by the attached Examiner's Paper No./Mail Date	Amendment / Comment or in the O	office action of
Identifying indicia such as the application number (see 37 CFR 1. each sheet. Replacement sheet(s) should be labeled as such in the	84(c)) should be written on the drawir ne header according to 37 CFR 1.121(o	ngs in the front (not the back) of d).
 DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT F 	sit of BIOLOGICAL MATERIAL n FOR THE DEPOSIT OF BIOLOGICA	nust be submitted. Note the AL MATERIAL.
Attachment(s) 1. ☐ Notice of References Cited (PTO-892)	5. ☐ Notice of Informal P	atent Application (PTO-152)
2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)	6. ☑ Interview Summary	(PTO-413),
Information Disclosure Statements (PTO-1449 or PTO/SB/08 Paper No./Mail Date	Paper No./Mail Dat 8), 7. ⊠ Examiner's Amendn	
4. Examiner's Comment Regarding Requirement for Deposit of Biological Material	8. 🛛 Examiner's Stateme	nt of Reasons for Allowance
S. S. Siografi Material	9.	
		BROOK KEBEDE
		PRIMARY EXAMINER

Application/Control Number: 10/815,934 Page 2

Art Unit: 2823

DETAILED ACTION

Terminal Disclaimer

1. The terminal disclaimer filed on December 6, 2005 disclaiming the terminal portion of any patent granted on this application which would extend beyond the expiration date of U.S. Application No. 10/808,298 has been reviewed and is accepted. The terminal disclaimer has been recorded.

EXAMINER'S AMENDMENT

2. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Mr. Richard V. Burgujian on January 19, 2006.

3. The application has been amended as follows:

In the Claims:

In Claim 3, line 20, change "this sealing" to --the sealing--.

In Claim 13, line 22, change "this sealing" to --the sealing--.

Allowable Subject Matter

4. Claims 2, 3, 12 and 13 allowed over prior art of record.

Reasons for Allowance

5. The following is an examiner's statement of reasons for allowance:

Application/Control Number: 10/815,934

Art Unit: 2823

The instant application claimed invention is allowed in view of the Terminal Disclaimer filed on December 6, 2005. In addition, the prior art of record neither anticipates nor renders obvious the claimed subject matter of the instant application as a whole either taken alone or in combination, in particular, prior art of record does not teach "fixing the semiconductor wafer onto the porous member by sucking the semiconductor wafer with at least, two systems of suction paths in association with the sucking areas in the direction in which the PSA tape is peeled off; and when the PSA tape is peeled off along the peeling direction and part of the PSA tape is peeled off in one of the sucking areas adjacent to each other, switching the suction paths therebetween in the vicinity of the other adjacent sucking area which the peeling of the PSA tape approaches so as to suck the semiconductor wafer, thereby fixing the semiconductor wafer onto the porous member in the other sucking area, the adhesive layer is cut in parallel with a control for switch between the at least two or more systems of suction paths in response to the state in-which the adhesive layer is cut," as recited in claim 2, "wherein the semiconductor wafer has a sealing resin formed on the first surface, and a low dielectric constant insulation film formed in contact with the sealing resin; the PSA tape is adhesively bonded onto the first surface of the semiconductor wafer via the sealing resin and the low dielectric constant insulation film; and the method further comprises fusing at least part of the low dielectric constant insulation film and the sealing resin so as to fix the low dielectric constant insulation film on the sealing resin," as recited in claim 3, "wafer with at least two systems of suction paths in association with the sucking areas in the direction in which the PSA tape is peeled off; and when the PSA tape is peeled off along the peeling direction and part of the PSA tape is peeled off in one of the sucking areas adjacent to each other, switching the suction paths therebetween in the vicinity of the other adjacent sucking area which the peeling of the PSA tape approaches so as to suck the semiconductor wafer, thereby fixing the

Page 3

Art Unit: 2823

semiconductor wafer onto the porous member in the other sucking area, the adhesive layer is cut in parallel with a control, for switch between the at least two or-more systems of suction paths in response to the state in which the adhesive layer is cut," as recited in claim 12, and "wherein the semiconductor wafer has a sealing resin formed on the first surface, and a low dielectric constant insulation film formed in contact with the sealing resin; the PSA tape is adhesively bonded onto the first surface of the semiconductor wafer via the sealing resin and the low dielectric constant insulation film; and the method further comprises fusing at least part of the low dielectric constant insulation film and the sealing resin so as to fix the low dielectric constant insulation film on the sealing resin," as recited in claim 13 respectively.

Conclusion

6. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Correspondence

7. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Brook Kebede whose telephone number is (571) 272-1862. The examiner can normally be reached on 8-5 Monday to Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Application/Control Number: 10/815,934

Art Unit: 2823

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Prook Kebede Primary Examiner Page 5

Art Unit 2823

BK

January 19, 2006